

MIXIM

28V, Low-Power, High-Voltage, **Boost or Inverting DC-DC Converter**

General Description

The MAX629 low-power DC-DC converter features an internal N-channel MOSFET switch and programmable current limiting. It is designed to supply positive or negative bias voltages up to ±28V from input voltages in the 0.8V to Vout range, and can be configured for boost, flyback, and SEPIC topologies.

The MAX629's current-limited pulse-frequency-modulation (PFM) control scheme provides high efficiency over a wide range of load conditions. An internal, 0.5A Nchannel MOSFET switch reduces the total part count, and a high switching frequency (up to 300kHz) allows for tiny surface-mount magnetics.

The MAX629's combination of low supply current, logiccontrolled shutdown, small package, and tiny external components makes it an extremely compact and efficient high-voltage biasing solution that's ideal for battery-powered applications. The MAX629 is available in an 8-pin SO package.

Applications

Positive or Negative LCD Bias Generators High-Efficiency DC-DC Boost Converters Varactor Tuning Diode Bias Palmtop Computers

2-Cell and 3-Cell Battery-Powered Applications

Features

- ♦ Internal, 500mA, 28V N-Channel Switch (No External FET Required)
- **♦** Generates Positive or Negative Output Voltages
- ♦ 80µA Supply Current
- ♦ 1µA Max Shutdown Current
- ♦ Up to 300kHz Switching Frequency
- **♦** Adjustable Current Limit Allows Use of Small, **Inexpensive Inductors**
- ♦ 8-Pin SO Package

Ordering Information

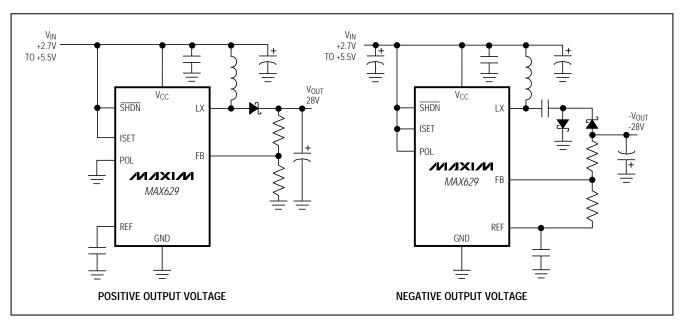
PART	TEMP. RANGE	PIN-PACKAGE	
MAX629C/D	0°C to +70°C	Dice*	
MAX629ESA	-40°C to +85°C	8 SO	

*Dice are tested at $T_A = +25$ °C, DC parameters only.

Note: To order tape-and-reel shipping, add "-T" to the end of the part number.

Pin Configuration appears at end of data sheet.

Typical Operating Circuit



NIXIN

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V_{CC} to GND)0.3V to +6V SHDN to GND0.3V to +6V ISET, REF, FB, POL to GND0.3V to (V_{CC} + 0.3V) LX to GND0.3V to +30V Continuous Power Dissipation ($T_A = +70^{\circ}C$)	Operating Temperature Range40°C to +85°C Junction Temperature+150°C Storage Temperature Range65°C to +165°C Lead Temperature (soldering, 10sec)+300°C
SO (derate 5.88mW/°C above +70°C)471mW	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +5V, C_{REF} = 0.1 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted.}$ Typical values are at $T_A = +25 ^{\circ}C.)$ (Note1)

PARAMETER CONDITIONS		NDITIONS	MIN	TYP	MAX	UNITS	
V _{CC} Input Voltage (Note 2)		2.7		5.5	V		
V _{CC} Supply Current	V _{FB} = 1.3V		80	120	μΑ		
V _{CC} Shutdown Current	SHDN = GND			0.04	1	μΑ	
V _{CC} Undervoltage Lockout	100mV hysteresis		2.3	2.5	2.65	V	
Input Supply Voltage (Note 2)	Voltage applied to L1 (V	(IN)	0.8		V _{OUT}	V	
CLIDAL DOL. ICET Logic Lovelo	VIH		2.4			\/	
SHDN, POL, ISET Logic Levels	VIL				0.4	V	
Positive Output Voltage	Circuit of Figure 2				28	V	
Negative Output Voltage	Circuit of Figure 3		- V _{IN}		-28	V	
LX Switch-Current Limit	ISET = VCC ISET = GND		0.39	0.45	0.51		
LX Switch-Current Limit			0.20	0.25	0.33	Α	
LX On-Resistance	V _{CC} = 5V			0.6	1.2	Ω	
LX OII-Resistance	V _{CC} = 3.3V			0.7	1.4		
LX Leakage Current	V _L X = 28V, T _A = +85°C	V _L X = 28V, T _A = +85°C			2.5	μΑ	
Maximum LX On-Time			6.5	8.5	10.0	μs	
	POL = GND		0.7	1.0	1.3	- μs	
Minimum LX Off-Time	POL = VCC		2.0	3.2	3.8		
Minimum LX OII-Time	POL = GND, V _{FB} < 1V		3.0	4.5	6.0		
	POL = V _{CC} , V _{FB} > 0.25V		3.0	4.5	6.0		
	POL = GND (positive output)	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	1.225	1.250	1.275	V	
FB Set Point		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	1.218		1.282		
FB Set Politi	POL = Vcc (negative output)	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	-15	0	15	- mV	
		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	-25		25		
FB Input Bias Current			5	50	nA		
REF Output Voltage	$V_{CC} = 2.7V \text{ to } 5.5V$		1.225	1.250	1.275	V	
KLI Output voltage	no load on REF	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	1.218		1.282	7 V	

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +5V, C_{REF} = 0.1 \mu F, T_A = -40 ^{\circ} C$ to $+85 ^{\circ} C$, unless otherwise noted. Typical values are at $T_A = +25 ^{\circ} C$.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
REF Load Regulation	$I_{REF} = 0\mu A \text{ to } 100\mu A, C_{REF} = 0.47\mu F \text{ (Note 3)}$		10	25	mV
Line Regulation	Circuit of Figure 2, V _{OUT} = 24V, V _{CC} = 3V to 5.5V, I _{LOAD} = 5mA		0.2		%/V
Load Regulation	Circuit of Figure 2, V _{OUT} = 24V, V _{CC} = 5V, I _{LOAD} = 0mA to 5mA		0.15		%
Thermal Shutdown Threshold	Die temperature		150		°C

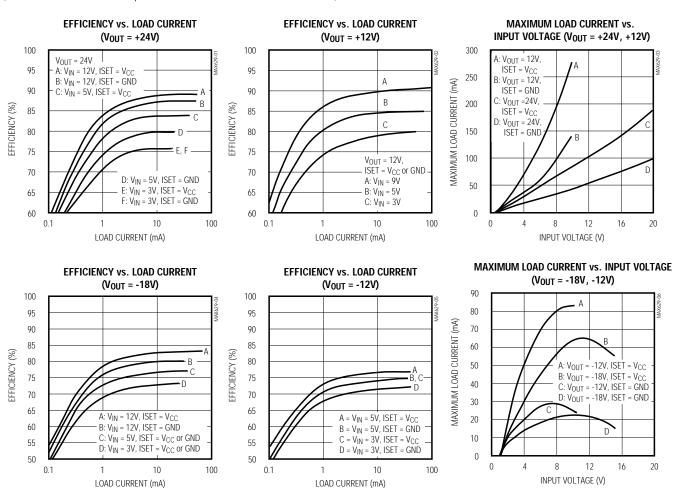
Note 1: Specifications to -40°C are guaranteed by design and not production tested.

Note 2: The IC itself requires a supply voltage between +2.7V and +5.5V; however, the voltage that supplies power to the inductor can vary from 0.8V to 28V, depending on circuit operating conditions.

Note 3: For reference currents less than 10μA, a 0.1μF reference-bypass capacitor is adequate.

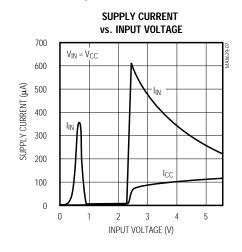
Typical Operating Characteristics

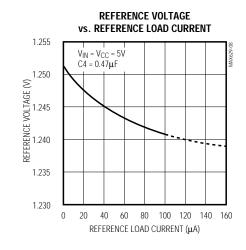
 $(\overline{SHDN} = V_{CC}, C_{REF} = 0.1 \mu F, T_A = +25 ^{\circ}C, unless otherwise noted.)$

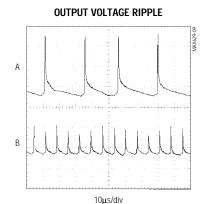


_Typical Operating Characteristics (continued)

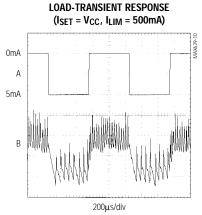
 $(\overline{SHDN} = V_{CC}, C_{REF} = 0.1 \mu F, T_A = +25 ^{\circ}C, unless otherwise noted.)$



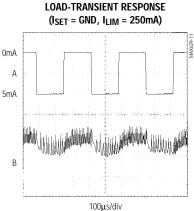






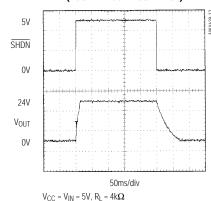


V_{OUT} = +24V, ISET = V_{CC} A: LOAD CURRENT, 0mA TO 5mA, 2.5mA/div B: V_{OUT}, AC-COUPLED, 10mV/div

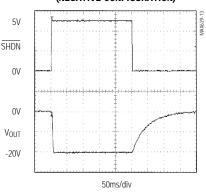


V_{OUT} = +24V, ISET = GND A: LOAD CURRENT, 0mA TO 5mA, 2.5mA/div B: V_{OUT}, AC-COUPLED, 10mV/div

SHUTDOWN TRANSIENT (POSITIVE CONFIGURATION)



SHUTDOWN TRANSIENT (NEGATIVE CONFIGURATION)



 $V_{CC} = V_{IN} = 5V$, $R_L = 4k\Omega$

Pin Description

PIN	NAME	FUNCTION
1	SHDN	Active-Low Shutdown Input. A logic low puts the MAX629 in shutdown mode and reduces supply current to 1μA.
2	POL	Polarity Input. Changes polarity and threshold of FB to allow regulation of either positive or negative output voltages. Set POL = GND for positive output voltage, or set POL = VCC for negative output voltage.
REF 1.25V Reference Output. Bypass to GND with a 0.1μF capacitor for $I_{REF} \le 10$ μA. REF can source 100μA drive external loads. For 10μA $\le I_{REF} \le 100$ μA, bypass REF with a 0.47μF capacitor.		
4	FB	Feedback Input for setting output voltage. Connect to an external voltage divider. See Setting the Output Voltage.
5	ISET	Current-Limit Set Input. Connect to V _{CC} for a 500mA LX current limit, or connect to GND for a 250mA LX current limit. See <i>Setting the Current Limit</i> .
6	GND	Ground
7	LX	Internal N-Channel DMOS Switch Drain
8	Vcc	Power-Supply Input

Detailed Description

The MAX629 low-power, boost DC-DC converter provides either positive or negative output voltages up to ±28V from a wide range of input voltages. It is designed primarily for use in low-power, high-voltage applications such as LCD biasing and set-top box varactor tuning. The MAX629's unique control scheme provides high efficiency and a wide range of output voltages with only 80µA quiescent supply current, making it ideal for battery-powered applications. The internal N-channel DMOS switch has a pin-programmable current limit (250mA and 500mA), allowing optimization of output current and component size. Figure 1 shows the MAX629 functional diagram.

Control Scheme

A combination of peak-current limiting and a pair of one-shots controls the MAX629 switching, determining the maximum on-time and constant off-time. During the on-cycle, the internal switch closes, and current through the inductor ramps up until either the fixed 10µs maximum on-time expires (at low input voltages) or the switch's peak current limit is reached. The peak switch current limit is selectable to either 500mA (ISET = VCC) or 250mA (ISET = GND) (see Setting the Current Limit). After the on-cycle terminates, the switch turns off, charging the output capacitor through the diode. In normal operation, the minimum off-time is set to 1µs for positive output voltages and 3.5µs for negative output voltages. When the output is well below reg-

ulation, however, the off-time is increased to 5µs to provide soft-start during start-up. The switching frequency, which depends upon the load, can be as high as 300kHz.

Shutdown Mode

When \overline{SHDN} is low, the MAX629 enters shutdown mode. In this mode, the feedback and control circuit, reference, and internal biasing circuitry turn off. The shutdown current drops to less than 1µA. \overline{SHDN} is a logic-level input; connect it to VCC for normal operation.

The output voltage behavior in shutdown mode depends on the output voltage polarity. In the positive output voltage configuration (Figure 2), the output is directly connected to the input through the diode (D1) and the inductor (L1). When the device is in shutdown mode, the output voltage falls to one diode drop below the input voltage, and any load connected to the output may still conduct current. In the negative output voltage configuration (Figure 3), there is no DC connection between the input and the output, and in shutdown mode the output is pulled to GND.

_Design Procedure

Setting the Output Voltage

For either positive or negative output voltage applications, set the MAX629's output voltage using two external resistors, R1 and R2, as shown in Figures 2 and 3. Since the input bias current at FB has a 50nA maximum value, large resistors can be used in the feedback loop

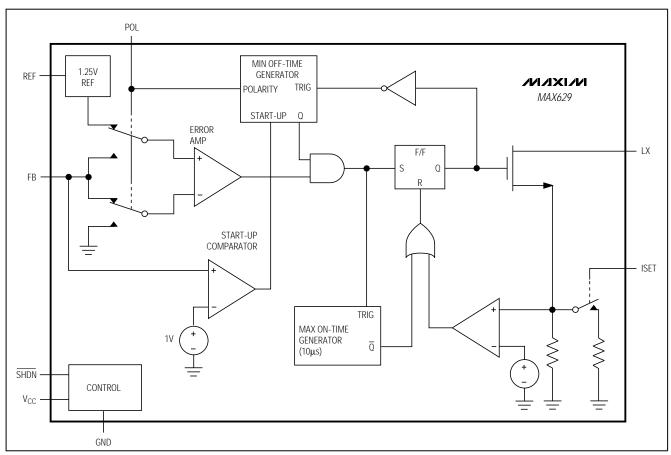


Figure 1. Functional Diagram

without a significant loss of accuracy. Begin by selecting R2 to be in the $10k\Omega$ to $200k\Omega$ range, and calculate R1 using the applicable equation from the following subsections.

Positive Output Voltages

For positive output voltages, use the typical boost configuration shown in Figure 2, connecting POL to GND. This sets the threshold voltage at FB to equal V_{REF}. Choose the value of R2 and calculate R1 as follows:

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

where $V_{REF} = 1.25V$.

Negative Output Voltages

For negative output voltages, configure R1 and R2 as shown in Figure 3, connecting POL to V_{CC} . This sets

the FB threshold voltage to GND so that negative voltages can be regulated. Choose R2 and calculate R1 as follows:

$$R1 = R2 \times \frac{|V_{OUT}|}{V_{RFF}}$$

where $V_{REF} = 1.25V$.

Figure 3 demonstrates generation of a negative output voltage by following the MAX629 with an inverting charge pump. This configuration limits $|V_{OUT}|$ to values between $-|V_{IN}|$ and -28V. If smaller negative output voltages are required, D2's cathode can be connected to V_{IN} . This alternative configuration permits output voltages smaller than $-|V_{IN}|$, but cannot be used for output voltages more negative than -|28V- $V_{IN}|$. It produces roughly one-half the output current as the standard configuration and is typically 5% less efficient.

Setting the Current Limit

External current-limit selection provides added control over the MAX629's output performance. A higher current limit increases the amount of energy stored in the inductor during each cycle, which provides a higher output current capability. For higher output current applications, choose the 500mA current-limit option by connecting ISET to VCC. When lower output current is required, the 250mA current limit can provide several advantages. First, a smaller inductor can be used, which saves board area and cost. Second, the smaller energy transfer per cycle reduces output ripple for a given capacitor, providing design flexibility between board area, cost, and output ripple by allowing cheaper, higher-ESR capacitors. Connect ISET to GND to select the 250mA current-limit option.

Inductor Selection

The MAX629's high switching frequency allows for the use of a small inductor. The 47µH inductor shown in the

Typical Operating Circuit is recommended for most applications. Larger inductances reduce the peak inductor current, but may limit output current capability at low input voltages and provide slower start-up times. Smaller inductances require less board space, but may cause greater peak current due to current-sense comparator propagation delay. If input voltages below 2V will be common, reducing the inductance to 22µH might improve performance; however, maximum load current and efficiency may decline. It is important to thoroughly test operation under all input and output conditions to ensure proper component selection.

Inductors with a ferrite core or equivalent are recommended; powder iron cores are not recommended for use with high switching frequencies. The inductor's incremental saturation rating must exceed the selected current limit. For highest efficiency, use an inductor with a low DC resistance (under $100m\Omega$). See Table 1 for a list of inductor suppliers.

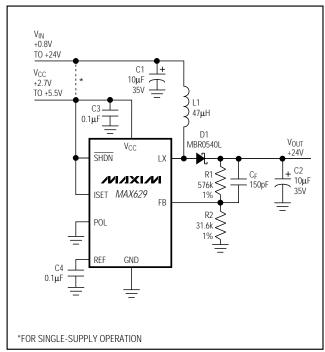


Figure 2. +24V for a Positive LCD Bias

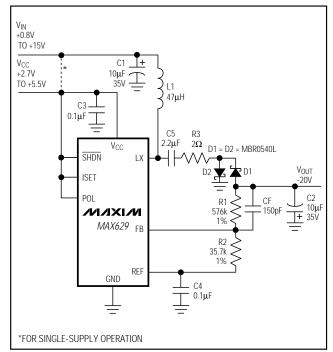


Figure 3. -20V for a Negative LCD Bias

Diode Selection

The MAX629's high switching frequency demands a high-speed rectifier. Schottky diodes, such as the 1N5819 or MBR0530L, are recommended. Make sure that the diode's peak current rating exceeds the peak current set by ISET, and that its breakdown voltage exceeds the output voltage. Schottky diodes are preferred due to their low forward voltage. However, ultrahigh-speed silicon rectifiers are also acceptable. Table 1 lists Schottky diode suppliers.

Capacitor Selection Output Filter Capacitor

The primary criterion for selecting the output filter capacitor is low effective series resistance (ESR). The product of the peak inductor current and the output filter capacitor's ESR determines the amplitude of the high-frequency ripple seen on the output voltage. These requirements can be balanced by appropriate selection of the current limit, as discussed in the Setting the Current Limit section. Table 1 lists some low-ESR capacitor suppliers. See the Output Voltage Ripple graph in the Typical Operating Characteristics section.

Input Bypass Capacitor

Although the output current of many MAX629 applications may be relatively small, the input must be designed to withstand current transients equal to the inductor current limit. The input bypass capacitor reduces the peak currents drawn from the voltage

Table 1. Component Suppliers

SUPPLIER	PHONE	FAX
CAPACITORS	1	
AVX: TPS series	(803) 946-0690	(803) 626-3123
Matsuo: 267 series	(714) 969-2491	(714) 960-6492
Sprague: 595D series	(603) 224-1961	(603) 224-1430
DIODES		
Motorola: MBR0530L	(602) 303-5454	(602) 994-6430
Nihon: EC11 FS1 series	(805) 867-2555	(805) 867-2698
INDUCTORS		
Coilcraft: DO1608 and DT1608 series	(847) 639-6400	(847) 639-1469
Murata-Erie: LQH4 series	(814) 237-1431	(814) 238-0490
Sumida: CD43, CD54, and CDRH62B series	(847) 956-0666	(847) 956-0702
TDK: NLC565050 series	(847) 390-4373	(847) 390-4428

source, and reduces noise caused by the MAX629's switching action. The input source impedance determines the size of the capacitor required at the input (VIN). As with the output filter capacitor, a low-ESR capacitor is recommended. A 10 μ F, low-ESR capacitor is adequate for most applications, although smaller bypass capacitors may also be acceptable. Bypass the IC separately with a 0.1 μ F ceramic capacitor placed as close as possible to the V_{CC} and GND pins.

Reference Capacitor

Bypass REF to GND with a $0.1\mu F$ ceramic capacitor for REF currents up to $10\mu A$. REF can source up to $100\mu A$ of current for external loads. For $10\mu A \leq I_{REF} \leq 100\mu A$, bypass REF with a $0.47\mu F$ capacitor.

Feed-Forward Capacitor

Parallel a capacitor (C_F) across R1 to compensate the feedback loop and ensure stability (Figures 2 and 3). Values up to 270pF are recommended for most applications. Choose the lowest capacitor value that ensures stability; high capacitance values may degrade line regulation.

Applications Information

Adjusting the Output Voltage

Many biasing applications require an adjustable output voltage, which is easily obtained using the configuration in Figure 4. In this circuit, an external bias voltage (which may be generated by a potentiometer, a DAC, or other means) is coupled to FB through the resistor RB. The output voltage of this circuit is given by:

$$V_{OUT} = V_{INIT} + \frac{R1}{R_B} (V_{FB} - V_{BIAS})$$

where $V_{\rm INIT}$ is the fixed output voltage as calculated in the section *Setting the Output Voltage*, and $V_{\rm FB}$ is equal to either $V_{\rm REF}$ (1.25V) for the positive configuration or 0V for the negative configuration. Proper choice of $R_{\rm B}$ provides a wide range of available output voltages using simple external components to generate $V_{\rm BIAS}$.

Input Voltage Range

Although, in many cases, the MAX629 and the inductor are powered from the same source, it is often advantageous in battery-powered applications to power the device from an available regulated supply and to power the inductor directly from a battery. The MAX629 requires a +2.7V to +5.5V supply at V_{CC} , but the inductor can be powered from as low as +0.8V, significantly

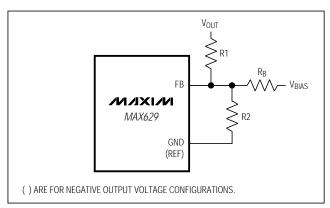


Figure 4. Adjustable Output Voltage

increasing usable battery life. Using separate supplies for V_{CC} and V_{IN} also reduces noise injection onto V_{CC} by isolating it from the switching transients, allowing a smaller, less-expensive input filter capacitor to be used in many applications. If input voltages below 2V will be common, reducing the inductor to $22\mu H$ may improve performance in this voltage range, at the potential cost of some decrease in maximum load current and efficiency.

In the negative configuration shown in Figure 3, the inverting charge pump injects current into LX with each cycle. The amount of charge injected increases at higher V_{IN} , and may prematurely trip the internal current-

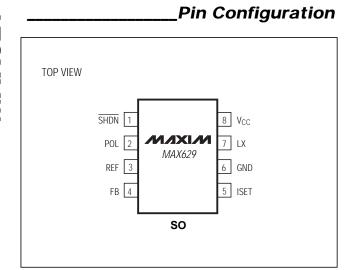
limit threshold. Resistor R3 increases the usable input voltage range by limiting the peak injected current. The 2Ω resistor shown provides a usable input voltage range beyond V_IN = 15V. In applications with a different input voltage range, R3 may be increased or decreased as necessary, with a resulting efficiency change of roughly 0.5%/ Ω .

Layout Considerations

Proper PC board layout is essential due to high current levels and fast switching waveforms that radiate noise. It is recommended that initial prototyping be performed using the MAX629 evaluation kit or equivalent PC board-based design. Breadboards or proto-boards should never be used when prototyping switching regulators.

It is important to connect the GND pin, the input bypass-capacitor ground lead, and the output filter-capacitor ground lead to a single point (star ground configuration) to minimize ground noise and improve regulation. Also, minimize lead lengths to reduce stray capacitance, trace resistance, and radiated noise, with preference given to the feedback circuit, the ground circuit, and LX. Place R1 and R2 as close to the feedback pin as possible. Place the input bypass capacitor as close as possible to VCC and GND.

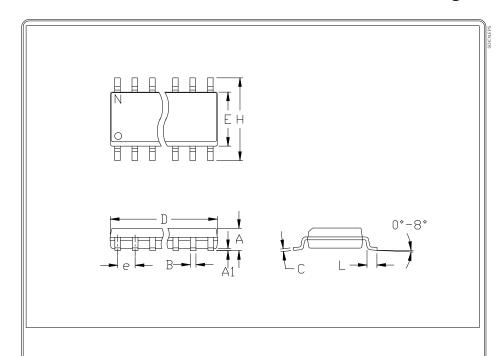
Refer to the MAX629 evaluation kit data sheet for an example of proper board layout.



_Chip Information

TRANSISTOR COUNT: 653
SUBSTRATE CONNECTED TO GND

Package Information



	INCHES		MILLIM	IETERS
	MIN	MAX	MIN	MAX
Α	0.053	0.069	1.35	1.75
Α1	0.004	0.010	0.10	0.25
В	0.014	0.019	0.35	0.49
С	0.007	0.010	0.19	0.25
6	0.050		1.27	
Ε	0.150	0.157	3.80	4.00
Н	0.228	0.244	5.80	6.20
h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27

	INCHES		MILLIMETERS			
	MIN	MAX	MIN	MAX	Z	MS012
D	0.189	0.197	4.80	5.00	8	Α
D	0.337	0.344	8.55	8.75	14	В
D	0.386	0.394	9.80	10.00	16	С

- NOTES:

 1. D&E DO NOT INCLUDE MOLD FLASH
 2. MOLD FLASH OR PROTRUSIONS NOT
 TO EXCEED .15mm (.006")

 3. LEADS TO BE COPLANAR WITHIN
 .102mm (.004")

 4. CONTROLLING DIMENSION: MILLIMETE

PACKAGE FAMILY DUTLINE: SDIC .150"



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NOTES